Layer Order

1. Signal 1, Comp. Side
2. Signal 2
3. Power
4. Signal 3
5. Signal 4
6. Ground
7. Signal 5
8. Signal 6, Solder Side

Board Characteristics:

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4, Tg > 170 ºC.
2. Minimum trace width 0.007" on all layers.
3. Minimum Clearance 0.007" on all layers.
4. 1 oz copper for all Trace and Power Layers.
5. Apply ENTEC or equivalent Organic Coating over bare copper.
   Apply Solder Mask over bare copper.
6. Board Thickness: 0.093 +/- 0.008".
7. Mill the Top and Bottom of board on the solder side to a thickness of 0.062" +/- 0.008".
8. Silkscreen on Component and Solder Sides.
9. 45 degree chamfer.
10. Hole diameter tolerances: +/- 0.002" unless specified otherwise.
11. Interlayer spacing: as specified.

Note 12: This is a pressfit technology thru hole with the following specification:

12-1. Finished hole size: 0.6mm +/- 0.05mm
12-2. Drilled hole size: 0.7mm +/- 0.02mm
12-3. Thickness of thru hole plating: min 25 µm Cu
12-4. Inside thru hole: OSP with 0.12 - 0.15 µm.